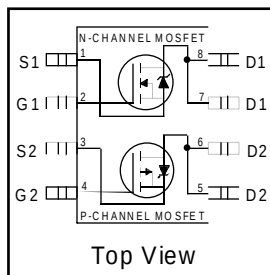


- Generation V Technology
- Ultra Low On-Resistance
- Dual N and P Channel MOSFET
- Surface Mount
- Fully Avalanche Rated

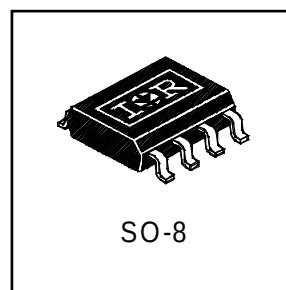
Description

Fifth Generation HEXFETs from International Rectifier utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET Power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The SO-8 has been modified through a customized leadframe for enhanced thermal characteristics and multiple-die capability making it ideal in a variety of power applications. With these improvements, multiple devices can be used in an application with dramatically reduced board space. The package is designed for vapor phase, infra red, or wave soldering techniques.



	N-Ch	P-Ch
V_{DS}	55V	-55V
$R_{DS(on)}$	0.050 Ω	0.105 Ω



Absolute Maximum Ratings

	Parameter	Max.		Units
		N-Channel	P-Channel	
V_{DS}	Drain-Source Voltage	55	-55	V
$I_D @ T_A = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$	4.7	-3.4	A
$I_D @ T_A = 70^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$	3.8	-2.7	
I_{DM}	Pulsed Drain Current ①	38	-27	
$P_D @ T_A = 25^\circ\text{C}$	Maximum Power Dissipation ⑤	2.0		W
$P_D @ T_A = 70^\circ\text{C}$	Maximum Power Dissipation ⑤	1.3		W
E_{AS}	Single Pulse Avalanche Energy ③	72	114	mJ
I_{AR}	Avalanche Current	4.7	-3.4	A
E_{AR}	Repetitive Avalanche Energy	0.20		mJ
V_{GS}	Gate-to-Source Voltage	± 20		V
dv/dt	Peak Diode Recovery dv/dt ②	5.0	-5.0	V/ns
T_J, T_{STG}	Junction and Storage Temperature Range	-55 to + 150		$^\circ\text{C}$

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Maximum Junction-to-Ambient ⑤	—	62.5	$^\circ\text{C/W}$

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter		Min.	Typ.	Max.	Units	Conditions
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	N-Ch	55	—	—	V	V _{GS} = 0V, I _D = 250μA
		P-Ch	-55	—	—		V _{GS} = 0V, I _D = -250μA
ΔV _{(BR)DSS} /ΔT _J	Breakdown Voltage Temp. Coefficient	N-Ch	—	0.059	—	V/°C	Reference to 25°C, I _D = 1mA
		P-Ch	—	0.054	—		Reference to 25°C, I _D = -1mA
R _{DS(ON)}	Static Drain-to-Source On-Resistance	N-Ch	—	0.043	0.050	Ω	V _{GS} = 10V, I _D = 4.5A ④
			—	0.056	0.065		V _{GS} = 4.5V, I _D = 3.8A ④
		P-Ch	—	0.095	0.105		V _{GS} = -10V, I _D = -3.1A ④
			—	0.150	0.170		V _{GS} = -4.5V, I _D = -2.6A ④
V _{GS(th)}	Gate Threshold Voltage	N-Ch	1.0	—	—	V	V _{DS} = V _{GS} , I _D = 250μA
		P-Ch	-1.0	—	—		V _{DS} = V _{GS} , I _D = -250μA
g _{fs}	Forward Transconductance	N-Ch	7.9	—	—	S	V _{DS} = 10V, I _D = 4.5A ④
		P-Ch	3.3	—	—		V _{DS} = -10V, I _D = -3.1A ④
I _{DSS}	Drain-to-Source Leakage Current	N-Ch	—	—	2.0	μA	V _{DS} = 55V, V _{GS} = 0V
		P-Ch	—	—	-2.0		V _{DS} = -55V, V _{GS} = 0V
		N-Ch	—	—	25		V _{DS} = 55V, V _{GS} = 0V, T _J = 55°C
		P-Ch	—	—	-25		V _{DS} = -55V, V _{GS} = 0V, T _J = 55°C
I _{GSS}	Gate-to-Source Forward Leakage	N-P	—	—	±100	nA	V _{GS} = ±20V
Q _g	Total Gate Charge	N-Ch	—	24	36		N-Channel I _D = 4.5A, V _{DS} = 44V, V _{GS} = 10V ④
		P-Ch	—	26	38		
Q _{gs}	Gate-to-Source Charge	N-Ch	—	2.3	3.4	nC	
		P-Ch	—	3.0	4.5		
Q _{gd}	Gate-to-Drain ("Miller") Charge	N-Ch	—	7.0	10		P-Channel I _D = -3.1A, V _{DS} = -44V, V _{GS} = -10V
		P-Ch	—	8.4	13		
t _{d(on)}	Turn-On Delay Time	N-Ch	—	8.3	12		N-Channel V _{DD} = 28V, I _D = 1.0A, R _G = 6.0Ω, R _D = 16Ω ④
		P-Ch	—	14	22		
t _r	Rise Time	N-Ch	—	3.2	4.8	ns	
		P-Ch	—	10	15		
t _{d(off)}	Turn-Off Delay Time	N-Ch	—	32	48		
		P-Ch	—	43	64		
t _f	Fall Time	N-Ch	—	13	20		P-Channel V _{DD} = -28V, I _D = -1.0A, R _G = 6.0Ω, R _D = 16Ω
		P-Ch	—	22	32		
C _{iss}	Input Capacitance	N-Ch	—	740	—	pF	N-Channel V _{GS} = 0V, V _{DS} = 25V, f = 1.0MHz
		P-Ch	—	690	—		
C _{oss}	Output Capacitance	N-Ch	—	190	—		
		P-Ch	—	210	—		
C _{rss}	Reverse Transfer Capacitance	N-Ch	—	71	—		P-Channel V _{GS} = 0V, V _{DS} = -25V, f = 1.0MHz
		P-Ch	—	86	—		

Source-Drain Ratings and Characteristics

	Parameter		Min.	Typ.	Max.	Units	Conditions
I _S	Continuous Source Current (Body Diode)	N-Ch	—	—	2.0	A	
		P-Ch	—	—	-2.0		
I _{SM}	Pulsed Source Current (Body Diode) ①	N-Ch	—	—	36		
		P-Ch	—	—	-25		
V _{SD}	Diode Forward Voltage	N-Ch	—	0.70	1.2	V	T _J = 25°C, I _S = 2.0A, V _{GS} = 0V ③
		P-Ch	—	-0.80	-1.2		T _J = 25°C, I _S = -2.0A, V _{GS} = 0V ③
t _{rr}	Reverse Recovery Time	N-Ch	—	60	90	ns	N-Channel T _J = 25°C, I _F = 2.0A, di/dt = 100A/μs ④
		P-Ch	—	54	80		
Q _{rr}	Reverse Recovery Charge	N-Ch	—	120	170	nC	
		P-Ch	—	85	130		T _J = 25°C, I _F = -2.0A, di/dt = 100A/μs

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 22)
- ② N-Channel I_{SD} ≤ 4.7A, di/dt ≤ 220A/μs, V_{DD} ≤ V_{(BR)DSS}, T_J ≤ 150°C
P-Channel I_{SD} ≤ -3.4A, di/dt ≤ -150A/μs, V_{DD} ≤ V_{(BR)DSS}, T_J ≤ 150°C
- ③ N-Channel Starting T_J = 25°C, L = 6.5mH R_G = 25Ω, I_{AS} = 4.7A.
P-Channel Starting T_J = 25°C, L = 20mH R_G = 25Ω, I_{AS} = -3.4A.
- ④ Pulse width ≤ 300μs; duty cycle ≤ 2%.
- ⑤ Surface mounted on FR-4 board, t ≤ 10sec.

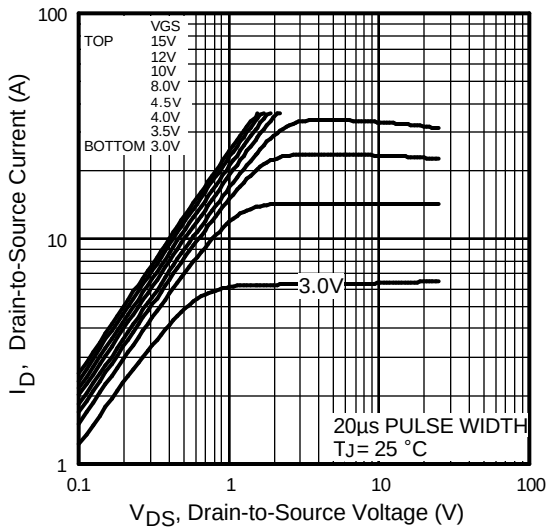


Fig 1. Typical Output Characteristics

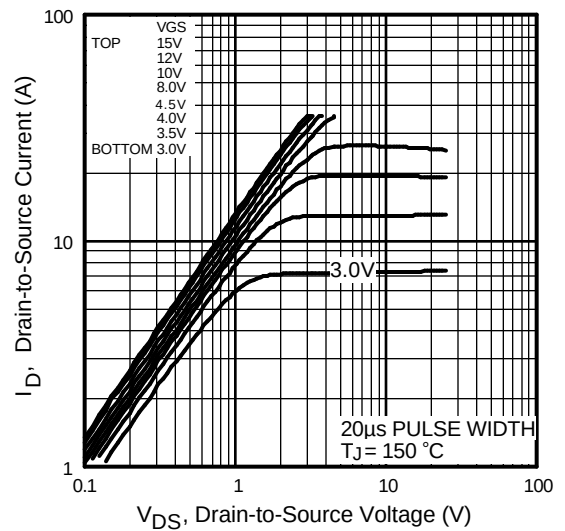


Fig 2. Typical Output Characteristics

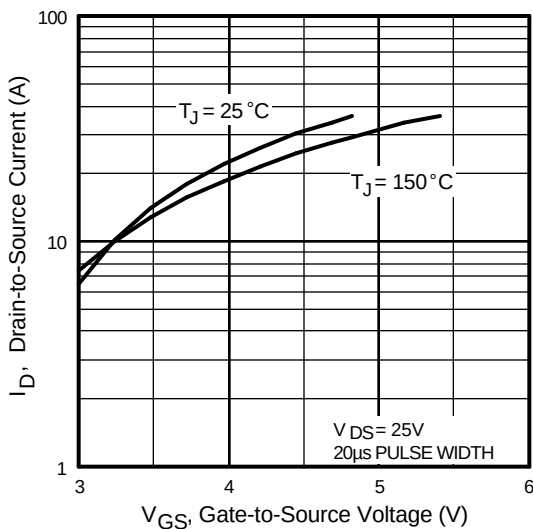


Fig 3. Typical Transfer Characteristics

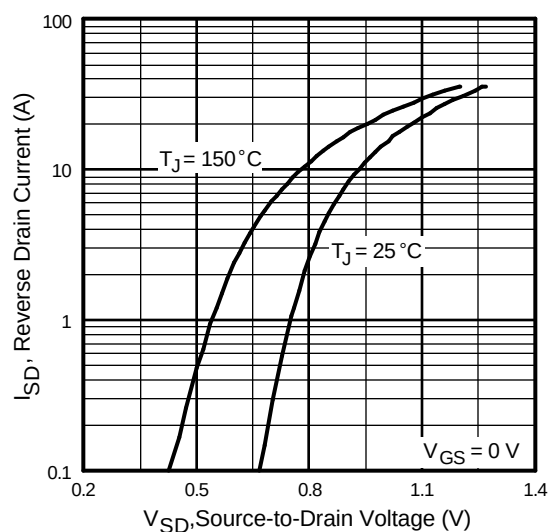


Fig 4. Typical Source-Drain Diode Forward Voltage

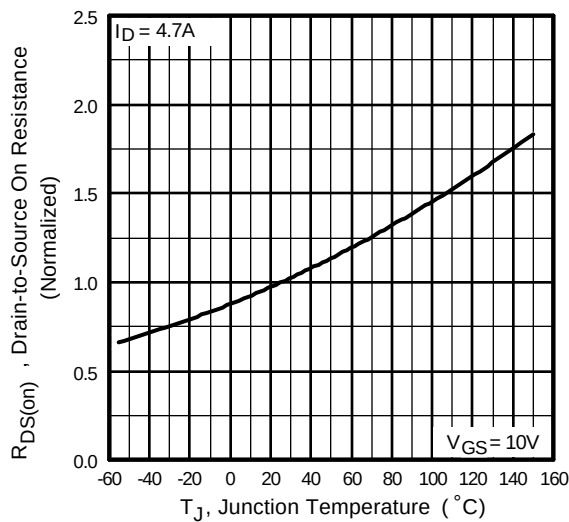


Fig 5. Normalized On-Resistance Vs. Temperature

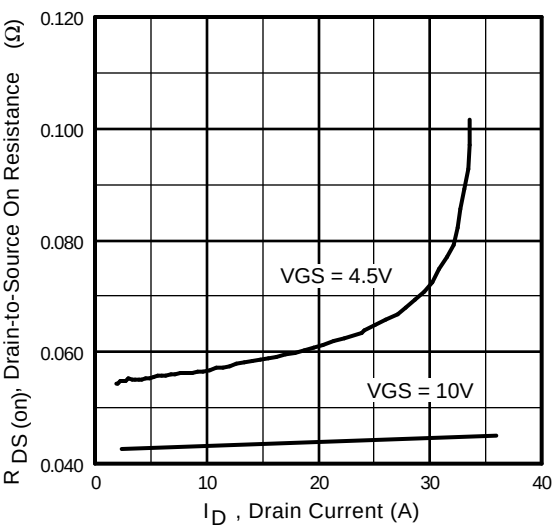


Fig 6. Typical On-Resistance Vs. Drain Current

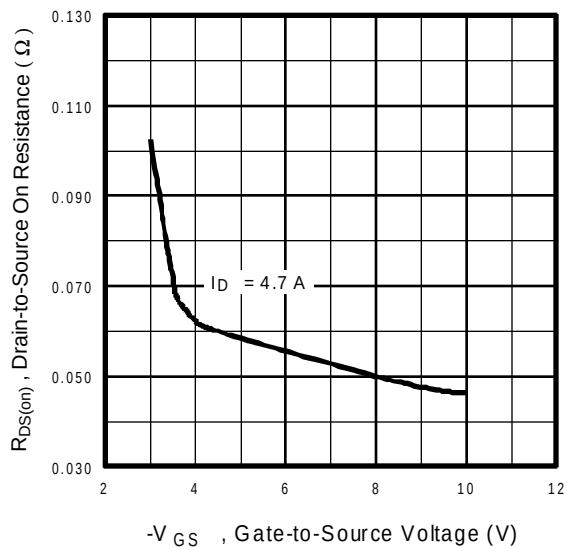


Fig 7. Typical On-Resistance Vs. Gate Voltage

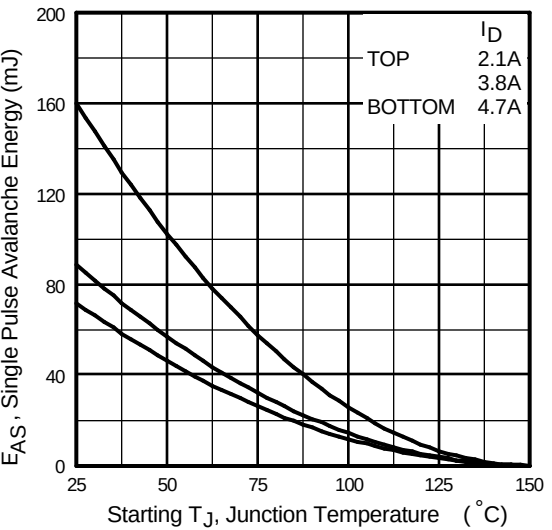


Fig 8. Maximum Avalanche Energy Vs. Drain Current

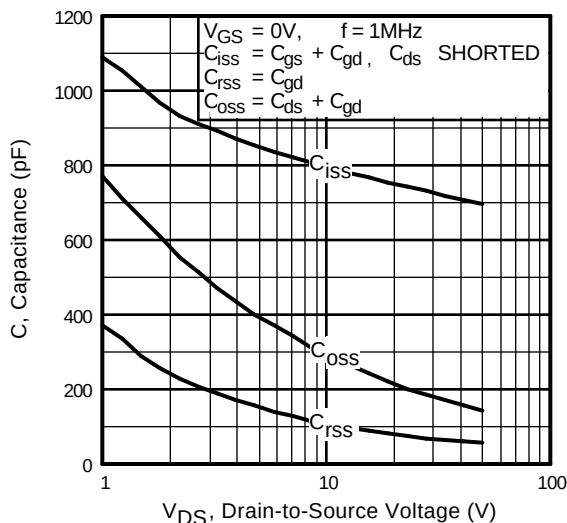


Fig 9. Typical Capacitance Vs. Drain-to-Source Voltage

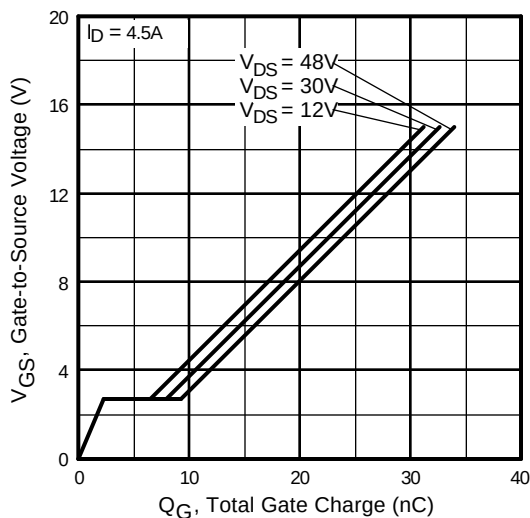


Fig 10. Typical Gate Charge Vs. Gate-to-Source Voltage

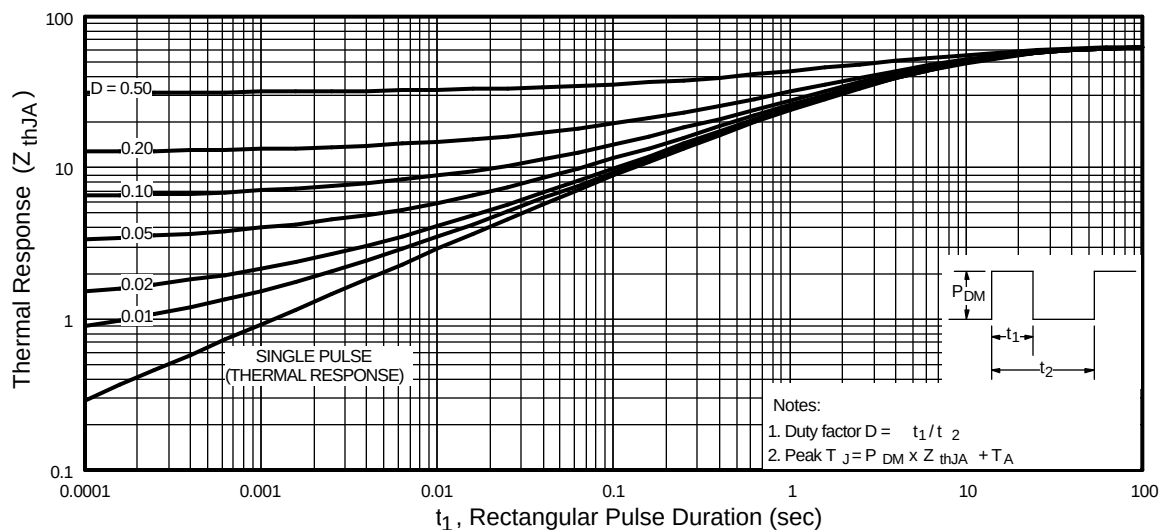


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

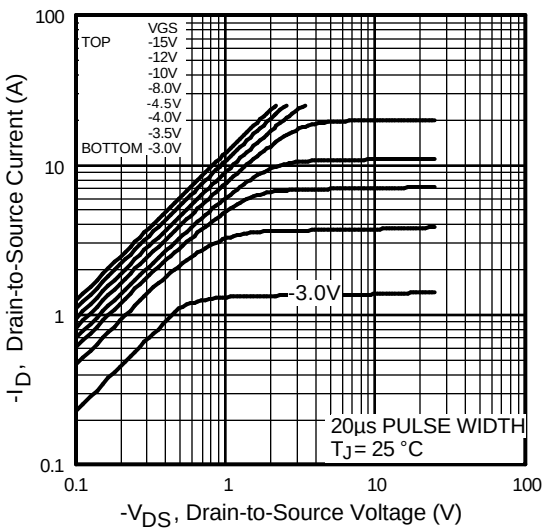


Fig 12. Typical Output Characteristics

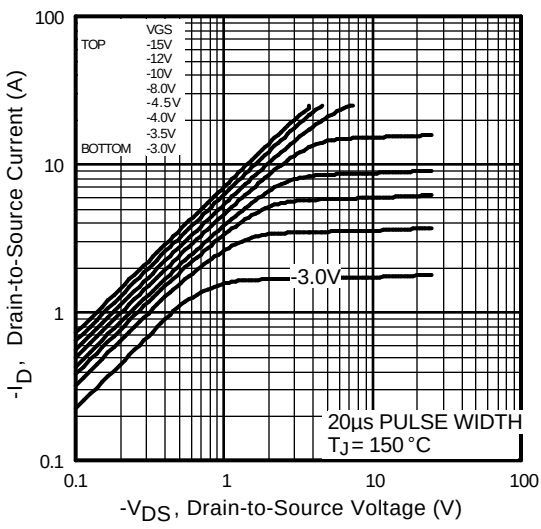


Fig 13. Typical Output Characteristics

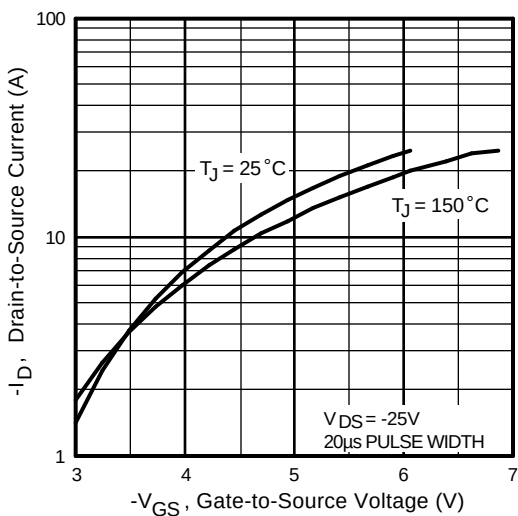


Fig 14. Typical Transfer Characteristics

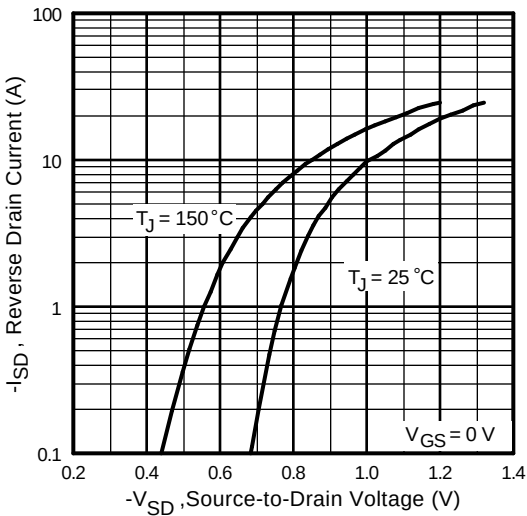


Fig 15. Typical Source-Drain Diode Forward Voltage

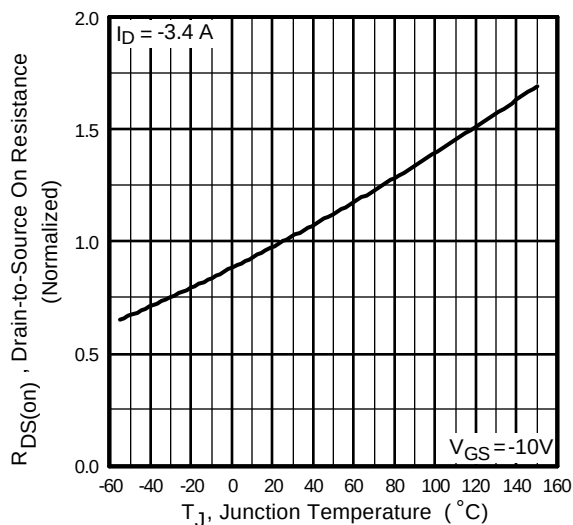


Fig 16. Normalized On-Resistance Vs. Temperature

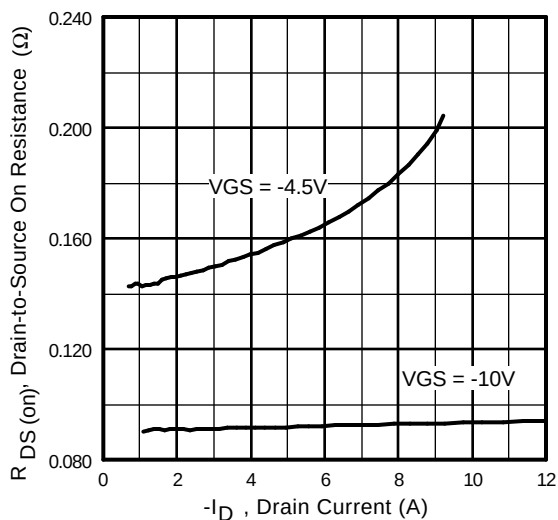


Fig 17. Typical On-Resistance Vs. Drain Current

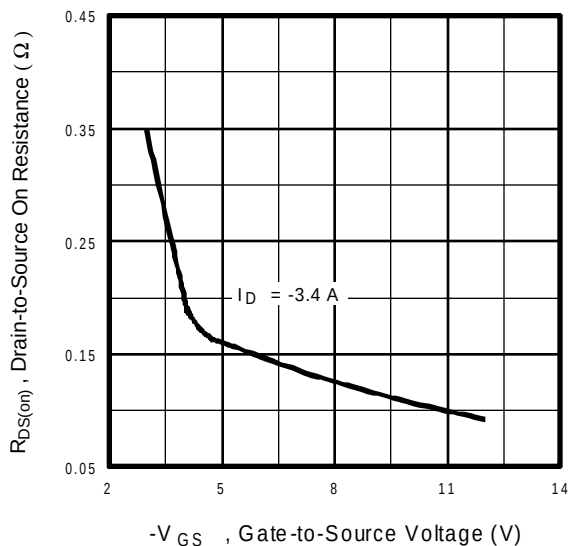


Fig 18. Typical On-Resistance Vs. Gate Voltage

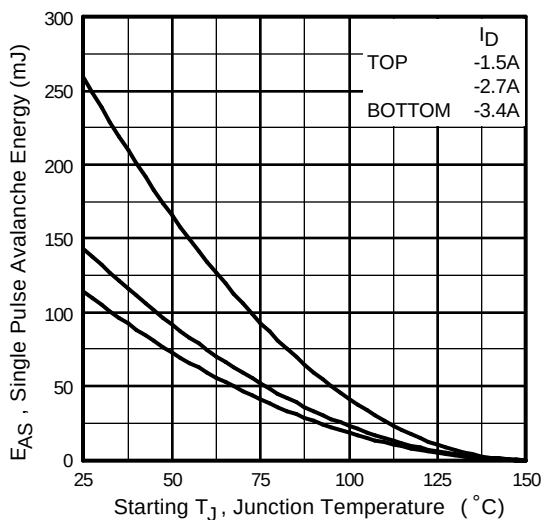


Fig 19. Maximum Avalanche Energy Vs. Drain Current

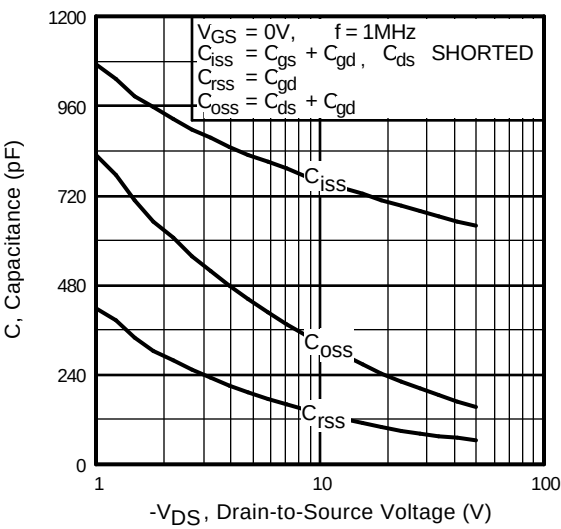


Fig 20. Typical Capacitance Vs. Drain-to-Source Voltage

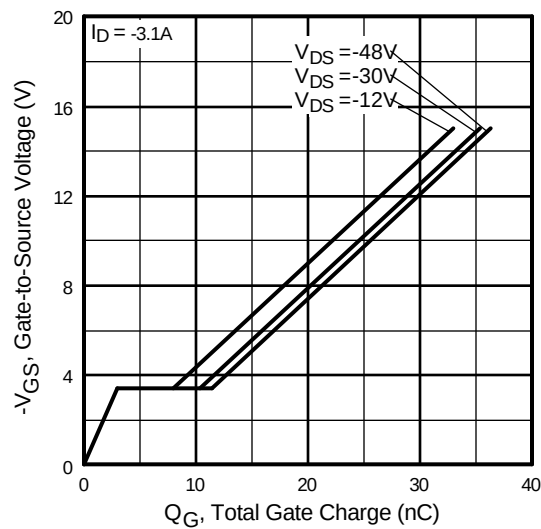


Fig 21. Typical Gate Charge Vs. Gate-to-Source Voltage

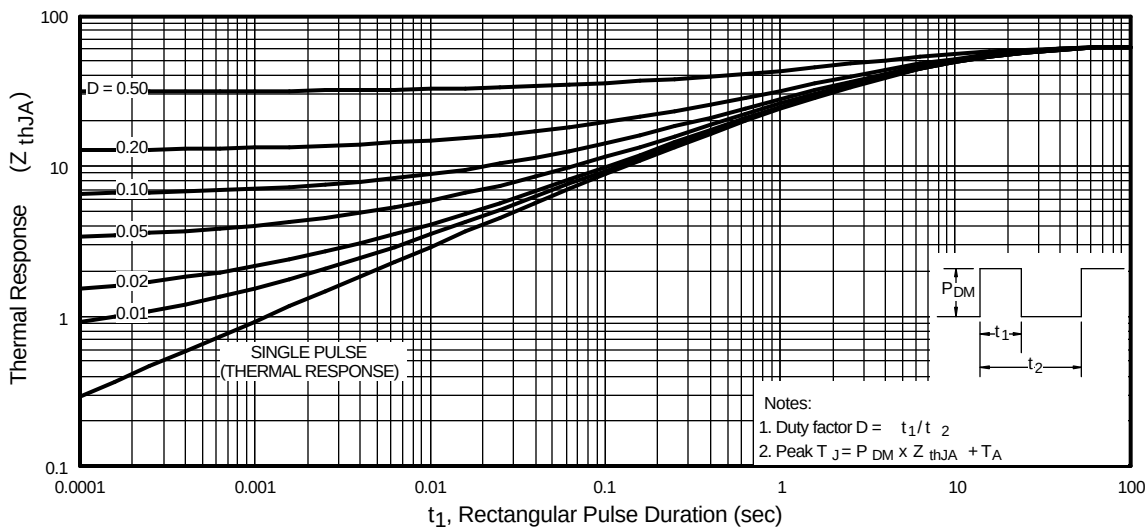
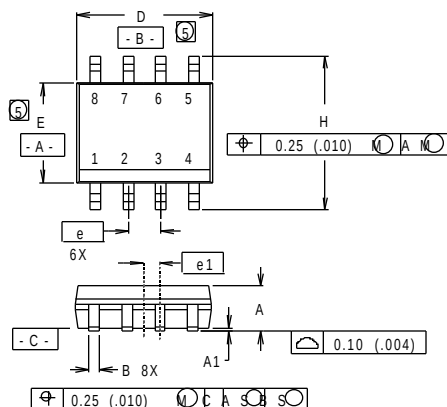


Fig 22. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

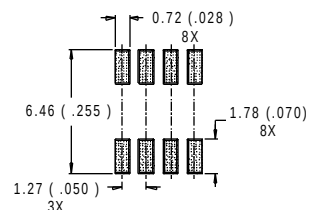
Package Outline

SO8 Outline



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
B	.014	.018	0.36	0.46
C	.0075	.0098	0.19	0.25
D	.189	.196	4.80	4.98
E	.150	.157	3.81	3.99
e	.050 BASIC		1.27 BASIC	
e1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.011	.019	0.28	0.48
L	0.16	.050	0.41	1.27
θ	0°	8°	0°	8°

RECOMMENDED FOOTPRINT



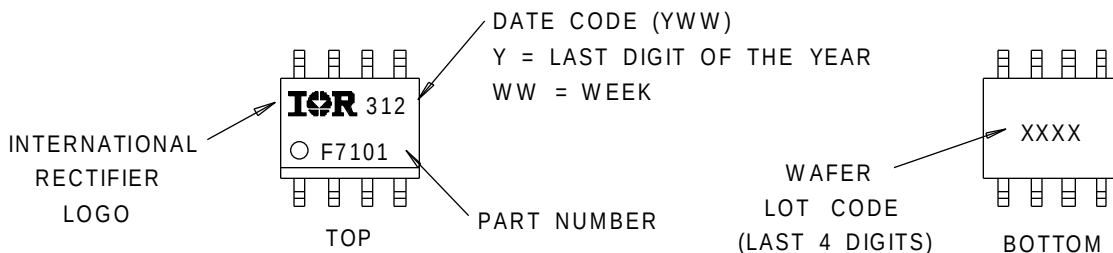
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
2. CONTROLLING DIMENSION : INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
- ⑤ DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS
MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.006).
- ⑥ DIMENSIONS IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE..

Part Marking Information

SO8

EXAMPLE : THIS IS AN IRF7101



Tape & Reel Information

S08

Dimensions are shown in millimeters (inches)

